

# XENSIV™ PAS CO2 Datasheet

## Description

Infineon has leveraged its knowledge in sensors and MEMS technologies to develop a disruptive gas sensor for CO2 sensing. The XENSIV™ PAS CO2 is a real CO2 sensor combining NDIR technology with Infineon’s high SNR MEMS microphones, allowing for state-of-the-art accuracy in an exceptionally small form factor.

The sensor is based on the photoacoustic spectroscopy (PAS) principle, where CO2 molecules within the sensor cavity absorb infrared light, generating small pressure changes that are detected by an acoustic detector. CO2 concentration is then delivered in the form of a direct ppm readout, thanks to the integrated microcontroller. Highly accurate CO2 readings are guaranteed.



## Features

- **Operating range:** 0 ppm to 32000 ppm
- **Accuracy:** ± (30 ppm +3%) of reading between 400 ppm and 3000 ppm
- **Maintenance:** Maintenance-free when using ABOC feature (Automatic Baseline Offset Correction)
- **Lifetime:** 10 years
- **Interface:** I2C, UART, and PWM
- **Package dimension:** 13.8 x 14 x 7.5 mm<sup>3</sup>
- **RoHs compliant**

## Potential applications

High accuracy, compact size, and SMD capability make the XENSIV™ PAS CO2 ideal for indoor air quality monitoring solutions in the market with numerous potential applications.

- **HVAC (Heating, Ventilation, Air Conditioning)**
- **Home appliances**
- **Smart home IoT devices**
- **Agriculture/ Greenhouses**
- **In-cabin air quality monitoring unit**



Table 1      Order information of PASCO2V01

| OPN Number     | SP Number   | RoHS Compliant |
|----------------|-------------|----------------|
| PASCO2V01AUMA3 | SP006037335 | Yes            |

Table of contents

Description ..... 1

Features ..... 1

Potential applications ..... 1

Table of contents ..... 2

1 Block diagram..... 3

2 Pin-out diagram ..... 4

3 The typical sensor response to the CO<sub>2</sub> concentration change ..... 5

4 Characteristics and parameters ..... 6

4.1 Specification ..... 6

4.1.1 Operating condition..... 6

4.1.2 Storage condition..... 6

4.1.3 Timing characteristics..... 7

4.1.4 Absolute maximum ratings..... 8

4.1.5 The current rating and power consumption ..... 8

4.1.6 CO<sub>2</sub> Transfer Function ..... 9

4.2 Peripheral timing..... 10

4.2.1 I2C characteristics ..... 10

4.2.2 UART characteristics ..... 13

4.3 Application Circuit Example..... 13

4.3.1 I2C application circuit example ..... 13

4.3.2 UART application circuit example ..... 14

4.3.3 PWM application circuit example ..... 14

4.4 Functional description ..... 15

4.4.1 Operating Modes ..... 15

4.4.2 Data post-processing..... 16

4.4.2.1 Pressure compensation ..... 16

4.4.2.2 Automatic Baseline Offset Correction ..... 16

4.4.2.3 Forced compensation ..... 16

4.4.2.4 Alarm Threshold..... 16

4.5 Monitoring mechanism as advanced functionality..... 17

4.6 Digital interface ..... 18

4.6.1 I2C interface ..... 18

4.6.2 I2C transaction format ..... 18

4.6.3 UART Interface..... 19

4.7 Register map..... 20

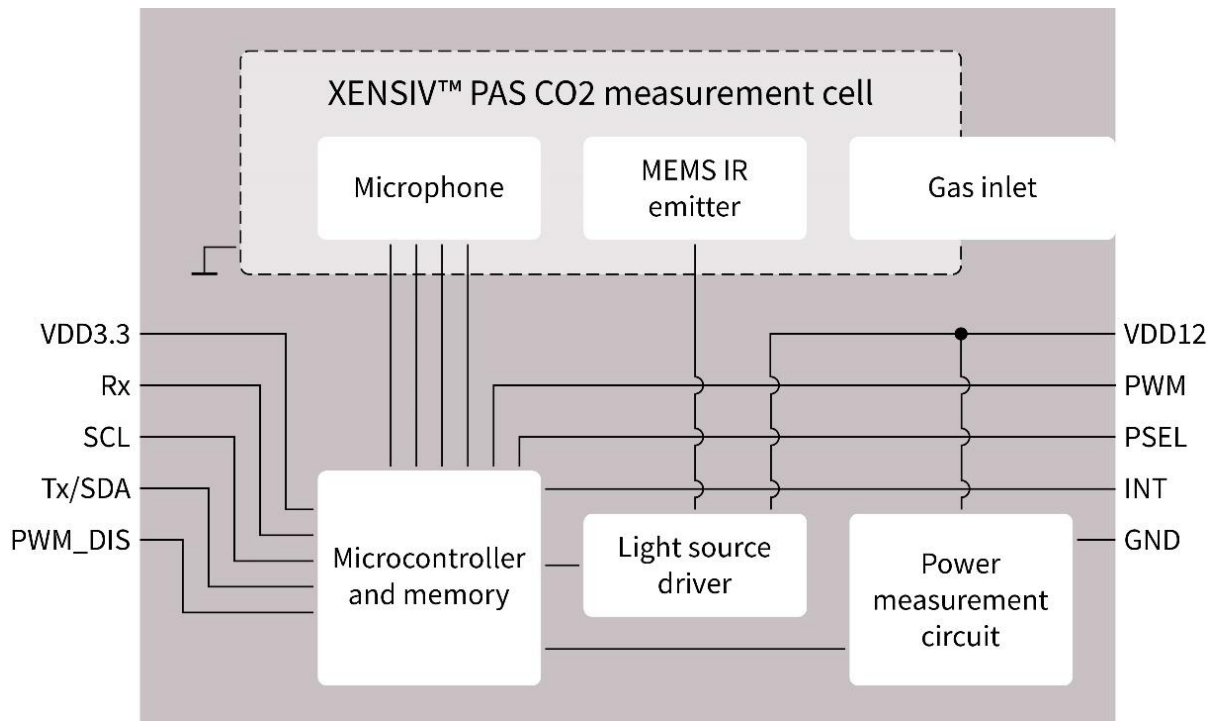
5 Assembly instruction ..... 21

6 Package information ..... 22

7 Packing for shipment..... 23

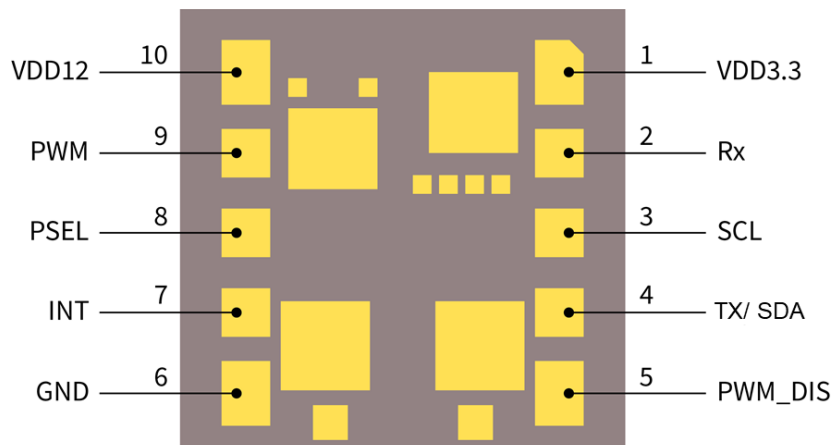
8 Revision history ..... 24

## 1 Block diagram



**Figure 1**      **Block diagram of XENSIV™ PAS CO2**

## 2 Pin-out diagram



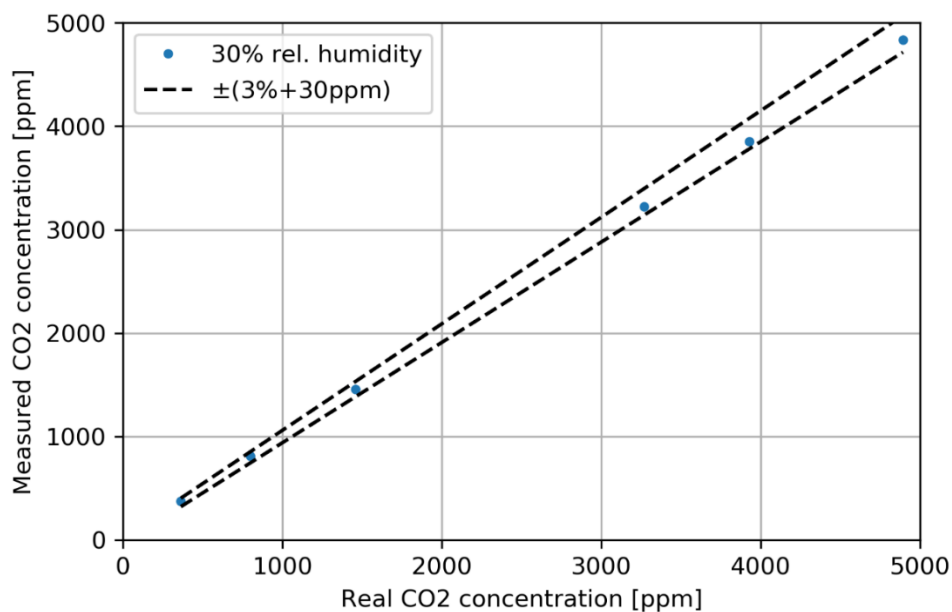
**Figure 2** Pin-out diagram (Bottom view)

**Table 2** Pin Description

| PIN | Symbol  | Type                | Description                                                     |
|-----|---------|---------------------|-----------------------------------------------------------------|
| 1   | VDD3.3  | Power supply (3.3V) | 3.3V digital power supply                                       |
| 2   | Rx      | Input/ Output       | UART receiver pin (3.3V domain)                                 |
| 3   | SCL     | Input/ Output       | I2C clock pin (3.3V domain)                                     |
| 4   | TX/ SDA | Output              | UART transmitter pin (3.3V domain) / I2C data pin (3.3V domain) |
| 5   | PWM_DIS | Input               | PWM disable input pin (3.3V domain)                             |
| 6   | GND     | Ground              | Ground                                                          |
| 7   | INT     | Output              | Interrupt output pin (3.3V domain)                              |
| 8   | PSEL    | Input               | Communication interface select input pin (3.3V domain)          |
| 9   | PWM     | Output              | PWM output pin (3.3V domain)                                    |
| 10  | VDD12   | Power supply (12V)  | 12V power supply for the IR emitter                             |

### 3 The typical sensor response to the CO<sub>2</sub> concentration change

Measurement condition: VDD12 = 12.0V, VDD3.3=3.3V, T<sub>amb</sub> = 25°C, P = 1013 hPa and %r.H. = 30%



**Figure 3** The typical sensor response to the CO<sub>2</sub> concentration change.

## 4 Characteristics and parameters

### 4.1 Specification

#### 4.1.1 Operating condition

All parameters specified in the following sections refer to these operating conditions unless otherwise specified.

**Table 3 Operating range**

| Parameter                                       | Symbol            | Values |      |       | Unit | Note or Test Condition         |
|-------------------------------------------------|-------------------|--------|------|-------|------|--------------------------------|
|                                                 |                   | Min.   | Typ. | Max.  |      |                                |
| CO <sub>2</sub> measurement range <sup>1)</sup> | C <sub>CO2</sub>  | 0      |      | 32000 | ppm  | Functional measurement range   |
| Ambient temperature <sup>1)</sup>               | T <sub>amb</sub>  | 0      |      | 50    | °C   |                                |
| Relative humidity <sup>1)</sup>                 | r.H.              | 0      |      | 85    | %    | Non-condensing                 |
| Pressure <sup>1)</sup>                          | p                 | 750    | 1013 | 1150  | hPa  |                                |
| Supply voltage <sup>1)</sup>                    | VDD3.3            | 3      | 3.3  | 3.6   | V    |                                |
|                                                 | VDD12             | 10.8   | 12   | 13.2  | V    |                                |
| Lifetime <sup>1)</sup>                          | t <sub>life</sub> |        | 10   |       | Year | Depends on the mission profile |

#### 4.1.2 Storage condition

Storage condition refers to Dry pack: Packed, non-evacuated, desiccant<sup>2)</sup>, Humidity Indicator Card (HIC) sealed moisture barrier bag.

**Table 4 Storage condition**

| Parameter                                          | Symbol                         | Values |      |      | Unit | Note or Test Condition  |
|----------------------------------------------------|--------------------------------|--------|------|------|------|-------------------------|
|                                                    |                                | Min.   | Typ. | Max. |      |                         |
| Storage temperature <sup>1)</sup>                  | T <sub>storage</sub>           | 5      |      | 40   | °C   | <90% r.H. <sup>3)</sup> |
| Storage time <sup>1)</sup>                         | t <sub>storage</sub>           |        |      | 3    | Year |                         |
| Storage temperature during transport <sup>1)</sup> | T <sub>storage_transport</sub> | -20    |      | 60   | °C   |                         |
| Storage time during transport <sup>1)</sup>        | t <sub>storage_transport</sub> |        |      | 10   | Day  |                         |

1) Not subject to production test. This parameter is verified by design/ characterization.

2) Number of desiccant units to be calculated according to JEDEC Standard 033.

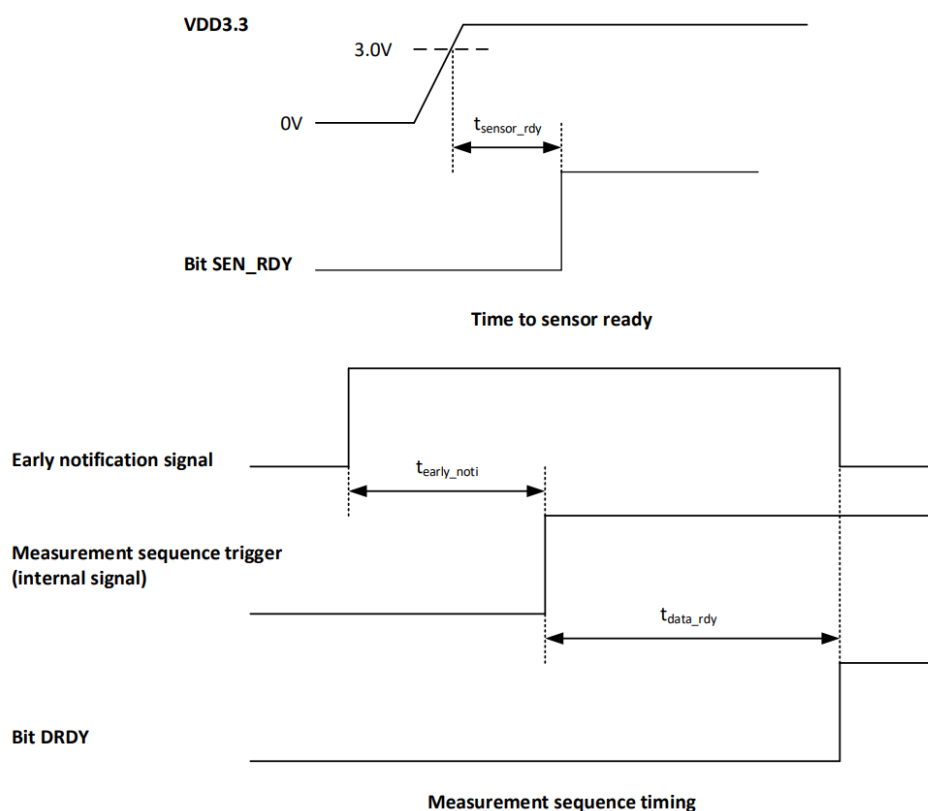
3) Condensation and bedewing shall be avoided.

### 4.1.3 Timing characteristics

**Table 5** Timing characteristics

| Parameter                                    | Symbol                   | Values |      |      | Unit | Note or Test Condition                                                        |
|----------------------------------------------|--------------------------|--------|------|------|------|-------------------------------------------------------------------------------|
|                                              |                          | Min.   | Typ. | Max. |      |                                                                               |
| Sampling time <sup>1)</sup>                  | $t_{\text{sampling}}$    | 10     | 60   | 4095 | s    | Sensor accuracy might be impacted for sampling rates faster than 1 meas/ min. |
| Time to sensor ready <sup>1)</sup>           | $t_{\text{sensor\_rdy}}$ |        |      | 1    | s    |                                                                               |
| Time to early notification <sup>1), 2)</sup> | $t_{\text{early\_noti}}$ |        | 2    |      | s    |                                                                               |
| I2C Clock frequency <sup>1)</sup>            | $f_{\text{I2C}}$         |        | 100  |      | kHz  |                                                                               |
|                                              |                          |        | 400  |      |      |                                                                               |
| PWM frequency <sup>1)</sup>                  | $f_{\text{pwm}}$         |        | 80   |      | Hz   |                                                                               |
| UART baud rate <sup>1)</sup>                 | $f_{\text{baud}}$        |        | 9.6  |      | kBps |                                                                               |

Typical measurement timing sequence has been illustrated in figure 4.



**Figure 4** Illustration of the timing characteristic parameters

1) Not subject to production test. This parameter is verified by design/ characterization.

2) Relevant for continuous mode of operation.

#### 4.1.4 Absolute maximum ratings

**Table 6** Absolute maximum ratings<sup>1)</sup>

| Parameter                   | Symbol               | Values |      |      | Unit | Note or Test Condition |
|-----------------------------|----------------------|--------|------|------|------|------------------------|
|                             |                      | Min.   | Typ. | Max. |      |                        |
| Moisture Sensitivity Level  | MSL                  |        | 3    |      |      |                        |
| Maximum ambient temperature | T <sub>amb_max</sub> | -10    |      | 60   | °C   |                        |
| Maximum relative humidity   | rH <sub>max</sub>    | 0      |      | 95   | %    |                        |
| 12V Supply voltage          | V <sub>VDD12</sub>   | 9.6    |      | 14.4 | V    |                        |
| 3.3V Supply voltage         | V <sub>VDD3.3</sub>  | 3.0    |      | 3.6  | V    |                        |
| Reflow temperature          | T <sub>r</sub>       |        |      | 245  | °C   | JEDEC J-STD-020E       |
| ESD Human Body Model        | V <sub>ESD_HBM</sub> | -2     |      | 2    | kV   | HBM (JS001)            |
| ESD Charge Discharge Model  | V <sub>ESD_CDM</sub> |        |      | 500  | V    | CDM (JS002)            |

**Note:** Stresses above the values listed as "Absolute Maximum Ratings" may cause permanent damage to the devices. Exposure to absolute maximum rating conditions for extended period of time may affect device reliability.

#### 4.1.5 The current rating and power consumption

All parameters specified in the following sections refer to the operating conditions unless otherwise specified: VDD3.3 = 3.3V, VDD12 = 12.0V, T<sub>amb</sub> = 25°C, % r.H. = 30 %, p = 1013 hPa and t<sub>sampling</sub> = 1 meas/ min.

**Table 7** Current rating

| Parameter                     | Symbol                | Pin    | Values |      |      | Unit | Note or Test Condition |
|-------------------------------|-----------------------|--------|--------|------|------|------|------------------------|
|                               |                       |        | Min.   | Typ. | Max. |      |                        |
| Peak current <sup>1)</sup>    | I <sub>peak 12</sub>  | VDD12  |        | 130  | 150  | mA   |                        |
| Peak current <sup>1)</sup>    | I <sub>peak 3.3</sub> | VDD3.3 |        | 10   |      | mA   |                        |
| Average current <sup>1)</sup> | I <sub>avg 12</sub>   | VDD12  |        | 0.8  |      | mA   |                        |
| Average current <sup>1)</sup> | I <sub>avg 3.3</sub>  | VDD3.3 |        | 6.1  |      | mA   |                        |
| Average power <sup>1)</sup>   | P <sub>avg</sub>      |        |        | 30   |      | mW   |                        |

Power consumption can be optimized further. For more details please refer to our application note section at the product [web page](#).

1) Not subject to production test. This parameter is verified by design/ characterization.

#### 4.1.6 CO<sub>2</sub> Transfer Function

All parameters specified in the following sections refer to the operating conditions unless otherwise specified:

VDD3.3 = 3.3V, VDD12 = 12.0V, T<sub>amb</sub> = 25°C, % r.H. = 30 %, p = 1013 hPa and t<sub>sampling</sub> = 1 meas/ min.

**Table 8 CO<sub>2</sub> Transfer Function**

| Parameter                        | Symbol               | Values                 |                           |                       | Unit  | Note or Test Condition                                          |
|----------------------------------|----------------------|------------------------|---------------------------|-----------------------|-------|-----------------------------------------------------------------|
|                                  |                      | Min.                   | Typ.                      | Max.                  |       |                                                                 |
| Accuracy <sup>1)</sup>           | Acc                  | -30 ppm- 3% of reading |                           | +30 ppm+3% of reading | ppm   | C <sub>CO2</sub> : 400 - 3000 ppm                               |
| Accuracy <sup>1)</sup>           | Acc                  |                        | ±(30 ppm + 3% of reading) |                       | ppm   | C <sub>CO2</sub> : 3001 - 5000 ppm                              |
| Response time <sup>2)</sup>      | t <sub>63</sub>      |                        | 90                        |                       | s     |                                                                 |
| Resolution <sup>2)</sup>         | Res                  |                        | 1                         |                       | ppm   |                                                                 |
| Repeatability <sup>2,3)</sup>    | R                    |                        |                           | 10                    | ppm   | 3 times standard deviation at fixed C <sub>CO2</sub> : 1000 ppm |
| Pressure stability <sup>2)</sup> | p <sub>error</sub>   |                        | 0                         |                       | %/hPa | With pressure compensation feature                              |
| Acoustic stability <sup>2)</sup> | SPL <sub>error</sub> | 3                      | 6                         | 15                    | ppm   | Up to 95 dB for Pink noise from 100 Hz to 10 kHz                |

- 1) Accuracy verified using certified calibration gas mixtures and high-precision reference sensors. Uncertainty in calibration gas mixtures of ±2% needs to be considered. Temporary deviations in accuracy caused by assembly, rough handling or harsh environmental conditions can be compensated using Forced Calibration Scheme (FCS) or Automatic Baseline Offset Correction (ABOC).
- 2) Not subject to production test. This parameter is verified by design/ characterization.
- 3) Stepwise Reactive IIR filter is enabled.

## 4.2 Peripheral timing

### 4.2.1 I2C characteristics

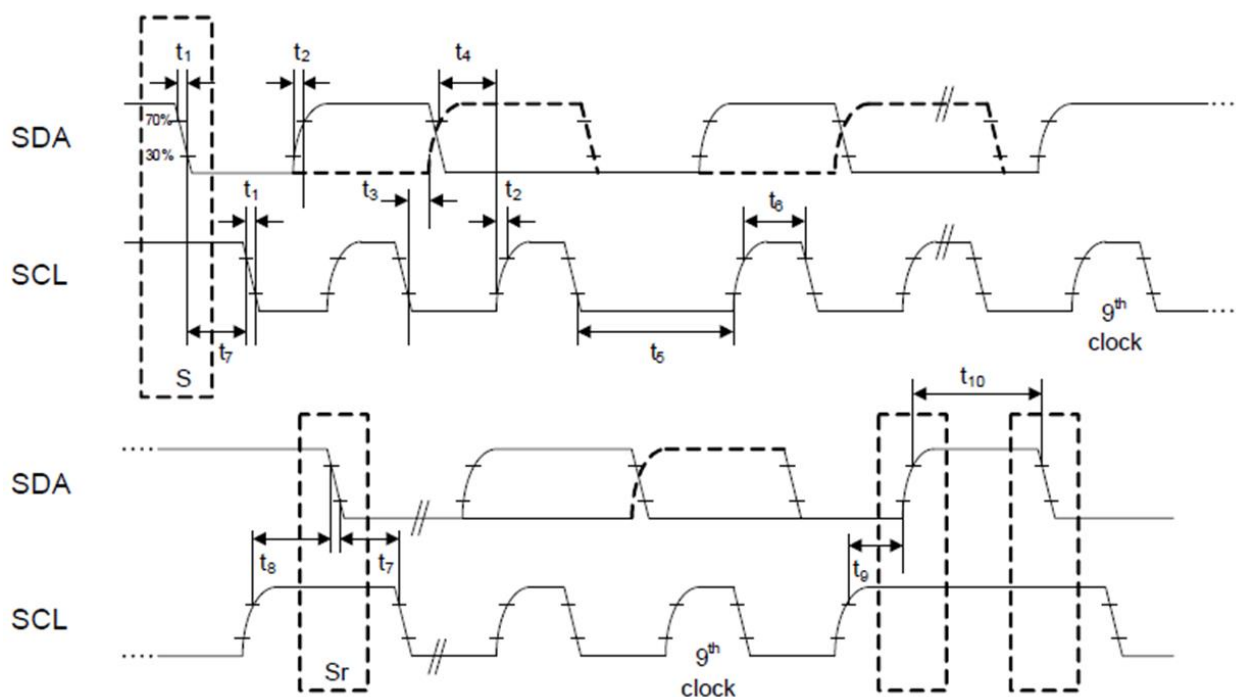
**Table 9 I2C Standard mode timing<sup>1)</sup>**

| Parameter                                        | Symbol          | Values |      |      | Unit | Note or Test Condition |
|--------------------------------------------------|-----------------|--------|------|------|------|------------------------|
|                                                  |                 | Min.   | Typ. | Max. |      |                        |
| Fall time of both SDA and SCL                    | t <sub>1</sub>  |        |      | 300  | ns   |                        |
| Rise time of both SDA and SCL                    | t <sub>2</sub>  |        |      | 1000 | ns   |                        |
| Data hold time                                   | t <sub>3</sub>  | 0      |      |      | μs   |                        |
| Data set-up time                                 | t <sub>4</sub>  | 250    |      |      | ns   |                        |
| LOW period of SCL clock                          | t <sub>5</sub>  | 4.7    |      |      | μs   |                        |
| HIGH period of SCL clock                         | t <sub>6</sub>  | 4.0    |      |      | μs   |                        |
| Hold time for a (repeated) START condition       | t <sub>7</sub>  | 4.0    |      |      | μs   |                        |
| Set-up time for (repeated) START condition       | t <sub>8</sub>  | 4.7    |      |      | μs   |                        |
| Set-up time for STOP condition                   | t <sub>9</sub>  | 4.0    |      |      | μs   |                        |
| Bus free time between a STOP and START condition | t <sub>10</sub> | 4.7    |      |      | μs   |                        |
| Capacitive load for each bus line                | C <sub>b</sub>  |        |      | 400  | pF   |                        |

- 1) Due to the wired-AND configuration of an I2C bus system, the port drivers on the SCL and SDA signal lines need to operate in open-drain mode. The high level of these lines must be held by an external pull-up device, approximately 10 kOhm for operation at 100 kbits/s, approximately 2 kOhm for operation at 400 kbits/s.

**Table 10** I2C fast mode timing<sup>1)</sup>

| Parameter                                        | Symbol          | Values                    |      |      | Unit | Note or Test Condition                                                |
|--------------------------------------------------|-----------------|---------------------------|------|------|------|-----------------------------------------------------------------------|
|                                                  |                 | Min.                      | Typ. | Max. |      |                                                                       |
| Fall time of both SDA and SCL                    | t <sub>1</sub>  | 20 + 0.1 * C <sub>b</sub> |      | 300  | ns   | C <sub>b</sub> refers to the total capacitance of one bus line in pF. |
| Rise time of both SDA and SCL                    | t <sub>2</sub>  | 20 + 0.1 * C <sub>b</sub> |      | 300  | ns   | C <sub>b</sub> refers to the total capacitance of one bus line in pF. |
| Data hold time                                   | t <sub>3</sub>  | 0                         |      |      | μs   |                                                                       |
| Data set-up time                                 | t <sub>4</sub>  | 100                       |      |      | ns   |                                                                       |
| LOW period of SCL clock                          | t <sub>5</sub>  | 1.3                       |      |      | μs   |                                                                       |
| HIGH period of SCL clock                         | t <sub>6</sub>  | 0.6                       |      |      | μs   |                                                                       |
| Hold time for a (repeated) START condition       | t <sub>7</sub>  | 0.6                       |      |      | μs   |                                                                       |
| Set-up time for (repeated) START condition       | t <sub>8</sub>  | 0.6                       |      |      | μs   |                                                                       |
| Set-up time for STOP condition                   | t <sub>9</sub>  | 0.6                       |      |      | μs   |                                                                       |
| Bus free time between a STOP and START condition | t <sub>10</sub> | 1.3                       |      |      | μs   |                                                                       |
| Capacitive load for each bus line                | C <sub>b</sub>  |                           |      | 400  | pF   |                                                                       |

**Figure 5** I2C Standard and Fast mode timing.

- 1) Due to the wired-AND configuration of an I2C bus system, the port drivers on the SCL and SDA signal lines need to operate in open-drain mode. The high level of these lines must be held by an external pull-up device, approximately 10 kΩ for operation at 100 kbits/s, approximately 2 kΩ for operation at 400 kbits/s.

## 4.2.2 UART characteristics

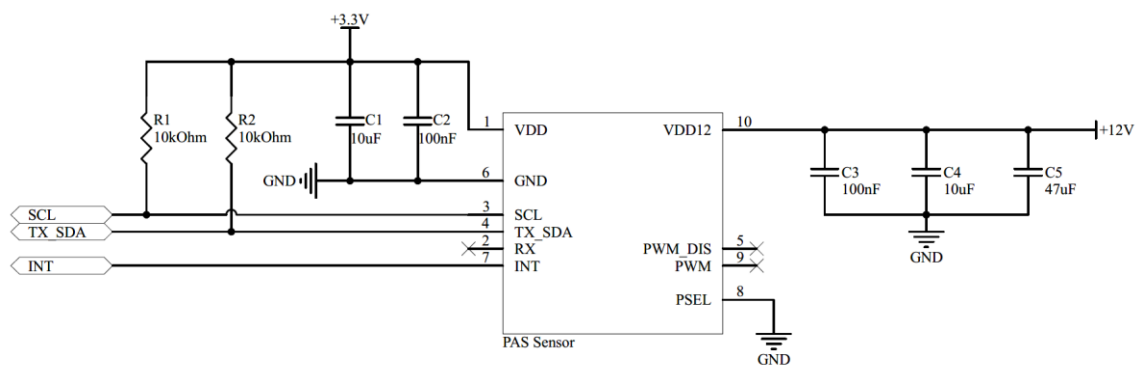
The main characteristics of the UART interface are described below:

- Point to point operation – no bus support.
- Slave operation only.
- $f_{\text{baud}} = 9.6 \text{ kBps}$
- Format: 1 start bit, 8 Data bits, no parity bit, 1 stop bit.
- Supports direct connection with terminal program.

For further details on UART and I2C communication protocol, please refer to our application note section in the product webpage.

## 4.3 Application Circuit Example

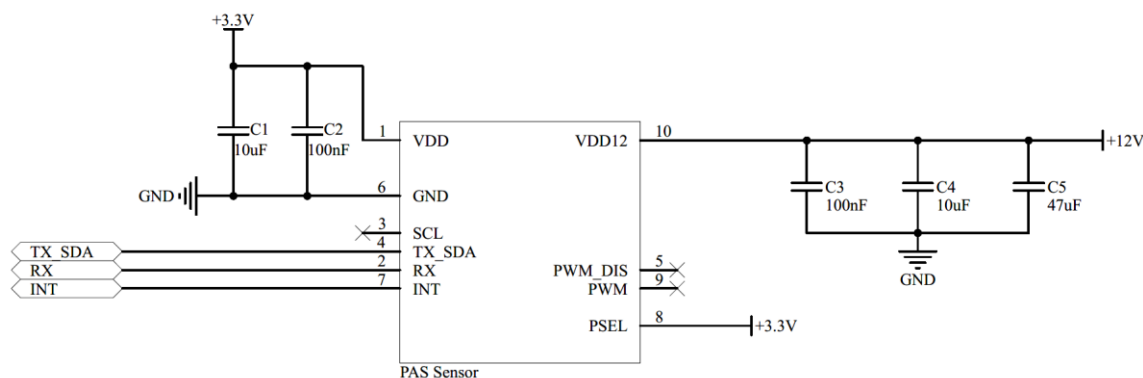
### 4.3.1 I2C application circuit example



**Figure 6** Application circuit example for I2C

With this configuration the device will start in idle mode of operation. Internal pull up is present on PWM\_DIS pin.

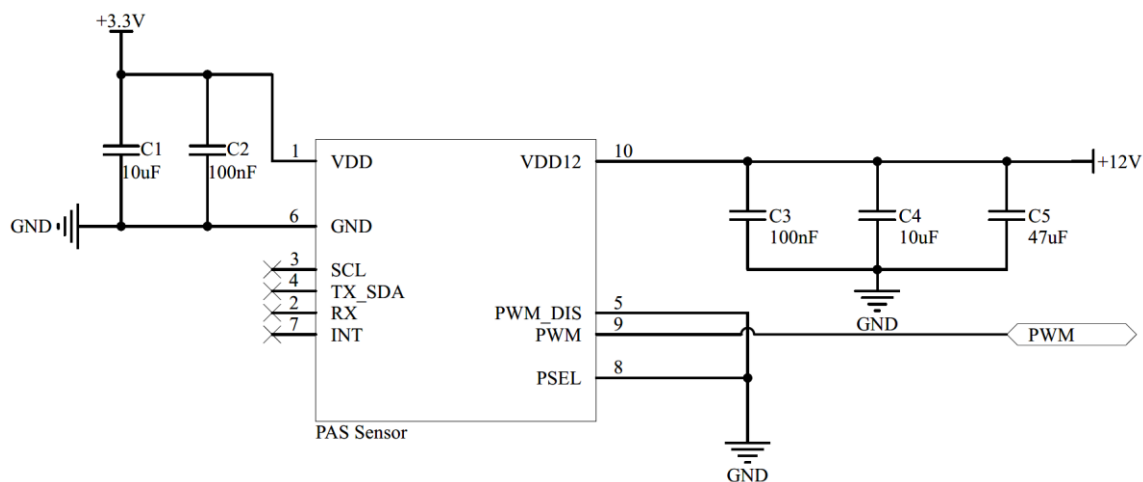
### 4.3.2 UART application circuit example



**Figure 7** Application circuit example for UART

With this configuration the device will start in idle mode of operation. Internal pull up is present on PWM\_DIS pin.

### 4.3.3 PWM application circuit example



**Figure 8** Application circuit example for PWM

## 4.4 Functional description

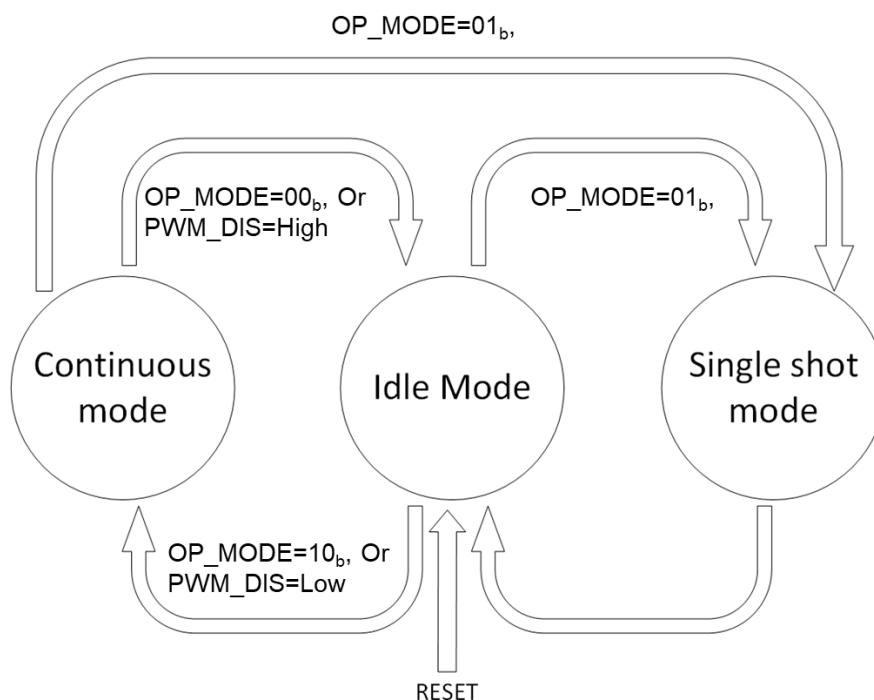
This section describes the operation of the sensor while measuring CO<sub>2</sub> concentrations. At any moment the device can be in one out of two different states: active and inactive. At active state, the CPU controlling the device is operating and can perform tasks such as: running a measurement sequence, serving an interrupt, etc. When the device has no specific task to perform, it goes to an inactive state. A transition from active to inactive state may occur at the end of a measurement sequence. In an inactive state, the CPU controlling the device is in sleep mode to optimize power consumption. Several events can wake up the device: the reception of a message on the serial communication interface, a falling edge on pin **PWM\_DIS**, the internal generation of a measurement request in continuous measurement mode.

### 4.4.1 Operating Modes

The operating mode can be programmed via the serial communication interface by using the bit field **MEAS\_CFG.OP\_MODE**.

The sensor module supports three operating modes:

- **Idle mode:** The device does not perform any CO<sub>2</sub> concentration measurement. The device remains inactive until it becomes active shortly to serve interrupts before going back to an inactive state.
- **Continuous mode:** In this mode, the device periodically triggers a CO<sub>2</sub> concentration measurement sequence. Once a measurement sequence is completed, the device goes back to an inactive state and wakes up automatically for the next measurement sequence. The measurement period is programmable from 5 sec to 4095 sec.
- **Single-shot mode:** In this mode, the device triggers a single measurement sequence. At the end of the measurement sequence, the device goes back automatically to idle mode.



**Figure 9** Operating mode transition

## 4.4.2 Data post-processing

Once the CO<sub>2</sub> concentration data has been acquired, several post-processing schemes can be applied to utilize different functionality.

### 4.4.2.1 Pressure compensation

The CO<sub>2</sub> concentration value acquired by the sensor is dependent on the external atmospheric pressure. To compensate for this effect, the application system can provide the value of the atmospheric pressure by writing into the specific registers, i.e. **PRESSREF\_H** and **PRESSREF\_L**. At the end of a measurement sequence, the device reads the pressure value and applies for compensation on the CO<sub>2</sub> concentration value before storing it into the result registers.

### 4.4.2.2 Automatic Baseline Offset Correction

To correct slow drifts caused by aging during operation, the device supports Automatic Baseline Offset Compensation. Every week of operation, the device computes an offset to correct the baseline of the device. The device must be in contact with the reference concentration (e.g. fresh air at 400 ppm of CO<sub>2</sub> concentration) at least 30 minutes per operating week to make sure proper baseline compensation. The device supports different configurations for compensation. **The ABOC setpoint may only be set between 350 and 1500 ppm.**

### 4.4.2.3 Forced compensation

Forced compensation provides a means to speed up the offset compensation process. Before forced compensation is enabled, the device shall be physically exposed to the reference CO<sub>2</sub> concentration. The device will use the **3 next measurements to calculate the compensation offset**. The user shall ensure constant exposure to the reference CO<sub>2</sub> concentration during that time. **It is recommended to operate at 1 measurement per 10 seconds while implementing the forced compensation scheme.** When 3 measurement sequences are completed, the device automatically reconfigures itself with the newly computed offset applied to the subsequent CO<sub>2</sub> concentration measurement results.

### 4.4.2.4 Alarm Threshold

The device can be configured via interrupt to perform an alarm threshold check each time a new CO<sub>2</sub> concentration data is acquired. At the end of each measurement sequence, the computed CO<sub>2</sub> value (after all applicable offset compensations) is compared to the concatenated value in **ALARM\_TH\_H** and **ALARM\_TH\_L**. In case of a threshold violation, the sticky bit **MEAS\_STS.ALARM** is set. This also sets pin **INT** to active level due to configuration as alarm. Bit **MEAS\_STS.ALARM** is cleared by reading register **MEAS\_STS.ALARM\_CLR**.

## 4.5 Monitoring mechanism as advanced functionality

The device supports several mechanisms to monitor the correct operation of the sensor.

**Table 11**      **Functionality description**

| Mechanism                         | Description                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                      |
|-----------------------------------|------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
| Sensor Ready status               | After each power-on reset, bit <b>SENS_STS.SEN_RDY</b> is set to confirm that the sensor has initialized correctly.                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                              |
| Scratchpad register               | <p>To check the integrity of the communication layer of the serial communication interface, register <b>SCRATCH_PAD</b> can be used. This register can use this memory field to write any value and verify that the data received by the device is correct.</p> <p>It can also be used to verify that a soft reset has been executed, using the following sequence:</p> <ol style="list-style-type: none"> <li>1. The user writes a non-default value to register <b>SCRATCH_PAD</b>.</li> <li>2. The user reads back register <b>SCRATCH_PAD</b> to verify the writ commend has been correctly executed.</li> <li>3. The user writes register <b>SENS_RST</b> to trigger a soft reset.</li> <li>4. The user reads register <b>SCRATCH_PAD</b> to verify that it has been reset to its default value.</li> </ol> |
| VDD12V verification               | At power-up and the beginning of each measurement sequence, the device measures automatically the voltage at <b>VDD12</b> . If the measured voltage exceeds the specified operating range of the device, bit <b>SENS_STS.ORVS</b> is set. The measurement sequence is however completed normally. Bit <b>SENS_STS.ORVS</b> can be cleared by setting bit <b>SENS_STS.ORVS_CLR</b>                                                                                                                                                                                                                                                                                                                                                                                                                                |
| Internal temperature verification | At the beginning of each measurement sequence, the device measures automatically its internal temperature. If the measured temperature exceeds the specified operating ranged of the device, sticky bit <b>SENS_STS.ORTMP</b> is set. The measurement sequence is however completed normally. Bit <b>SENS_STS.ORTMP</b> can be cleared by setting bit <b>SENS_STS.ORTMP_CLR</b> .                                                                                                                                                                                                                                                                                                                                                                                                                                |

## 4.6 Digital interface

The XENSIV™ PAS CO<sub>2</sub> supports I2C, UART, and PWM. The communication protocols have been covered in separate application notes.

### 4.6.1 I2C interface

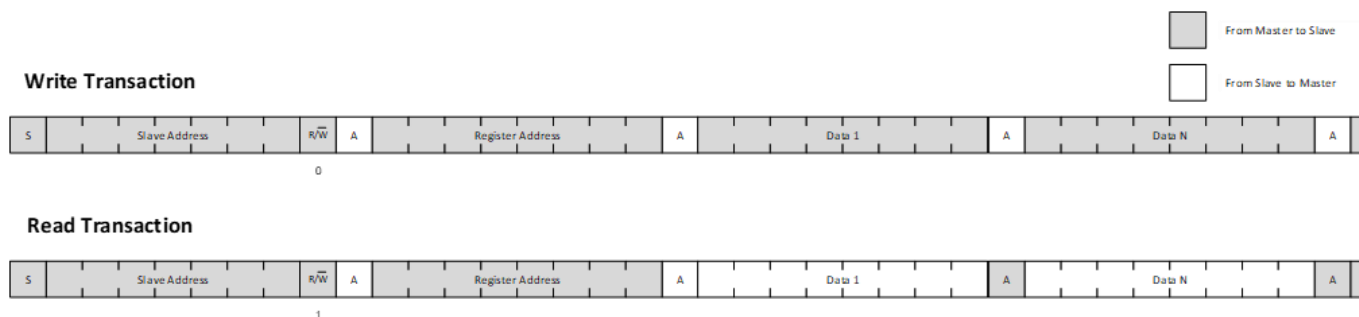
The device complies with the I2C protocol. When I2C is selected as a serial communication interface, the device acts as an I2C slave. The main characteristics of the interface are described below:

- Slave mode only.
- I2C Clock frequency: 100 kHz and 400 kHz
- 7-bit slave address: 0x28
- No CRC.
- The device supports clock stretching.
- 8bit addressing mode supported (7bit address + RW)
- Bulk read and write supported (device auto-increments automatically the address).
- Address 0x00 not supported.

Further details of the protocol are covered in the separate application note.

### 4.6.2 I2C transaction format

The I2C transaction has the following structure: a start condition followed by four bytes followed a stop condition.



**Figure 10** I2C write and read transaction

**Table 12** I2C transaction

| Byte | Description     | Value                              | Comments                                                             |
|------|-----------------|------------------------------------|----------------------------------------------------------------------|
|      | Start condition |                                    |                                                                      |
| 1    | Header          | (Slave Address << 1)   R/W         |                                                                      |
| 2    | First data-byte | As per user request/register value | Read: data provided by the slave<br>Write: data provided by the user |
| N+2  | Data byte N     | As per user request/register value | Read: data provided by the slave<br>Write: data provided by the user |
|      | End condition   |                                    |                                                                      |

### 4.6.3 UART Interface

When UART is selected as a serial communication interface, the device acts as a UART slave. The device operates via UART for point-to-point communication. Bus operation is not supported. As a result, it is recommended that the master uses a time-out mechanism. The basic format of a valid UART frame is 1 start bit, 8 data bits, no parity bit, and 1 stop bit. The master combines several UART frames into a message (read or write). The combination of master request and slave answer defines a transaction. The main characteristics of the interface are described below:

- Point to point operation – no bus support.
- Slave operation only.
- UART clock frequency = 9.6 kHz
- Format: 1 start bit, 8 Data bits, no parity bit, 1 stop bit. Supports direct connection with a terminal program.

For further details on UART communication, please have a look into our relevant application note titled as 'Programming guide for XENSIV™ PAS CO2' in the application note section on the product website.

## 4.7 Register map

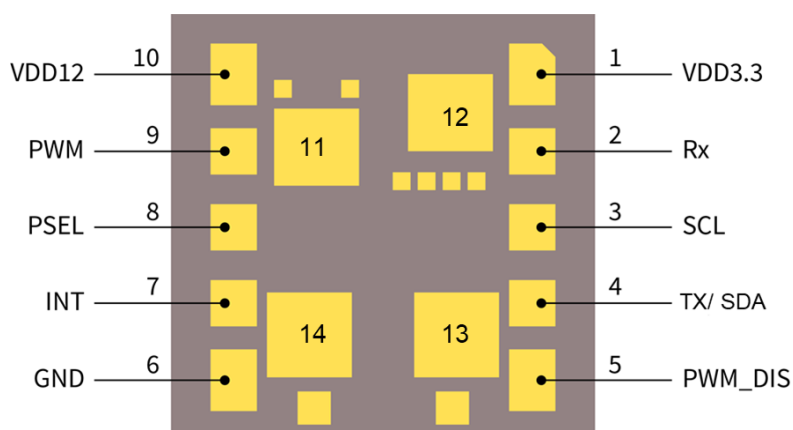
| Name        | Address             | Bit 7                                                                                              | Bit 6            | Bit 5           | Bit 4          | Bit 3          | Bit 2          | Bit 1            | Bit 0           | Reset |
|-------------|---------------------|----------------------------------------------------------------------------------------------------|------------------|-----------------|----------------|----------------|----------------|------------------|-----------------|-------|
| PROD_ID     | 0x00                | PROD<br>r                                                                                          |                  |                 | REV<br>r       |                |                |                  |                 | 0x4F  |
| SENS_STS    | 0x01                | SEN_RDY<br>rh                                                                                      | PWM_DIS_ST<br>rh | ORTMP<br>rhs    | ORVS<br>rhs    | ICCR<br>rhs    | ORTMP_CLR<br>w | ORVS_CLR<br>w    | ICCR_CLR<br>w   | 0xC0  |
| MEAS_RATE_H | 0x02                | VAL<br>rwh                                                                                         |                  |                 |                |                |                |                  |                 | 0x00  |
| MEAS_RATE_L | 0x03                | VAL<br>rwh                                                                                         |                  |                 |                |                |                |                  |                 | 0x3C  |
| MEAS_CFG    | 0x04                | 0<br>rw                                                                                            |                  | PWM_OUTEN<br>rw | PWM_MODE<br>rw | BOC_CFG<br>rwh |                | OP_MODE<br>rwh   |                 | 0x24  |
| CO2PPM_H    | 0x05                | VAL<br>r                                                                                           |                  |                 |                |                |                |                  |                 | 0x00  |
| CO2PPM_L    | 0x06                | VAL<br>r                                                                                           |                  |                 |                |                |                |                  |                 | 0x00  |
| MEAS_STS    | 0x07                | 0<br>rw                                                                                            |                  | Res<br>rh       | DRDY<br>rhs    | INT_STS<br>rhs | ALARM<br>rhs   | INT_STS_CLR<br>w | ALARM_CLR<br>w  | 0x00  |
| INT_CFG     | 0x08                | 0<br>rw                                                                                            |                  |                 | INT_TYP<br>rw  | INT_FUNC<br>rw |                |                  | ALARM_TYP<br>rw | 0x11  |
| ALARM_TH_H  | 0x09                | VAL<br>rw                                                                                          |                  |                 |                |                |                |                  |                 | 0x00  |
| ALARM_TH_L  | 0x0A                | VAL<br>rw                                                                                          |                  |                 |                |                |                |                  |                 | 0x00  |
| PRESS_REF_H | 0x0B                | VAL<br>rwh                                                                                         |                  |                 |                |                |                |                  |                 | 0x03  |
| PRESS_REF_L | 0x0C                | VAL<br>rwh                                                                                         |                  |                 |                |                |                |                  |                 | 0xF7  |
| CALIB_REF_H | 0x0D                | VAL<br>rwh                                                                                         |                  |                 |                |                |                |                  |                 | 0x01  |
| CALIB_REF_L | 0x0E                | VAL<br>rwh                                                                                         |                  |                 |                |                |                |                  |                 | 0x90  |
| SCRATCH_PAD | 0x0F                | VAL<br>rw                                                                                          |                  |                 |                |                |                |                  |                 | 0x00  |
| SENS_RST    | 0x10                | SRTRG<br>w                                                                                         |                  |                 |                |                |                |                  |                 | 0x00  |
| Reserved    | 0x11<br>...<br>0x14 | Reserved registers<br>Read & Write access to those registers generate a communication error        |                  |                 |                |                |                |                  |                 |       |
| Reserved    | 0x15<br>...<br>0xFF | Reserved registers<br>Read & Write access to those registers generate a non-acknowledge condition. |                  |                 |                |                |                |                  |                 |       |

Complete 'Register-map description' has been covered in a separate application note titled as 'Register-map description of XENSIV™ PAS CO2' in the product webpage.

## 5 Assembly instruction

XENSIV™ PAS CO<sub>2</sub> module is classified as Moisture-Sensitivity Level 3 (MSL 3). The maximum reflow temperature during board assembly must not exceed 245°C according to IPC/JEDEC J-STD-020E. As shown in the figure 11, Pad 1 to 14 need to be soldered. Pad 1 to 10 need to be assembled as per functionality. Pad 11 and 13 need to be connected to the GND. Pad 12 and 14 are not internally connected but must be soldered to maintain mechanical stability. Pad 12 and 14 can be left open or connected to GND. Non-marked smaller pads should be kept open.

Further details such as footprint drawing, board assembly guidelines, stencil recommendation can be found into CO<sub>2</sub> product page under Infineon package name '[LG-MLGA-14](#)'.



**Figure 11** XENSIV™ PAS CO<sub>2</sub> pads need to be connected to an application board.

*Note:*

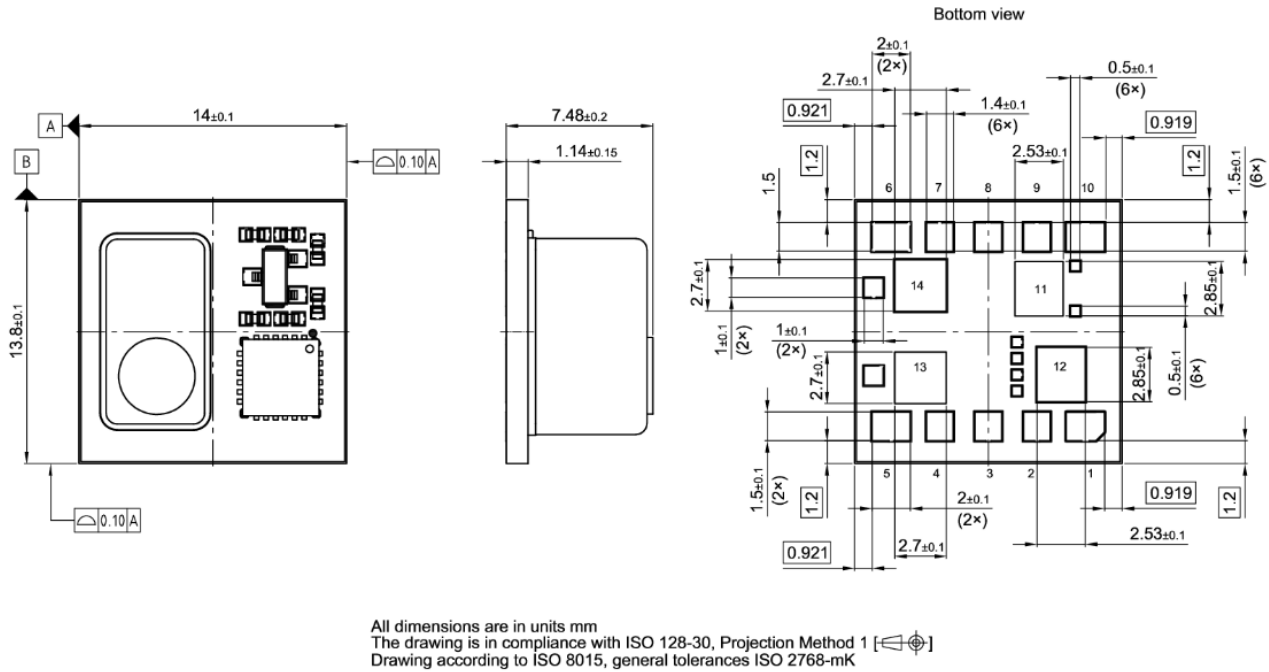
- 1) One-time reflow is permitted and after assembly rework is not recommended.
- 2) Vapor phase soldering may damage the sensor irreversibly.

For the customer, the allocated floor time (Out of bag) is 168 hours (at ≤30°C and 60% r.H.) according to IPC/JEDEC J-STD-020. If floor time exceeds, then the parts (Out of moisture barrier bag) need to be baked according to the following table:

**Table 13** Baking condition of the XENSIV™ PASCO<sub>2</sub>

| Package condition       | Bake temperature | Bake time | Condition |
|-------------------------|------------------|-----------|-----------|
| Sensors outside of tape | 125°C            | 24 hours  | r.H. < 5% |
| Sensors within the tape | 40°C             | 8 days    | r.H. < 5% |

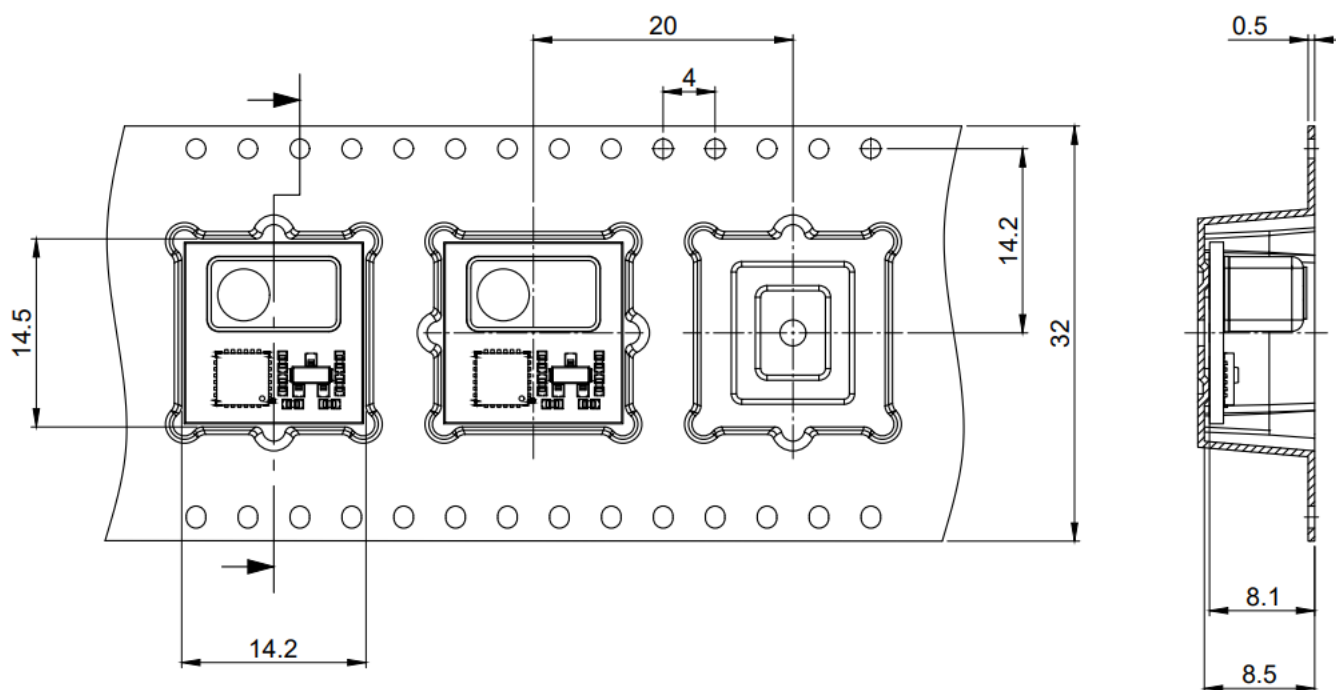
## 6 Package information



**Figure 12**      **Package dimensions of XENSIV™ PAS CO2.**

## 7 Packing for shipment

The device will be shipped in tape and reel. Each tape and reel consist of 300 parts.



All dimensions are in units mm

The drawing is in compliance with ISO 128-30, Projection Method 1 [  ]

**Figure 13** Tape and reel packing of XENSIV™ PAS CO<sub>2</sub>

## 8 Revision history

**Table 14 Datasheet versions tracking**

| Reference | Description                                                                                                                                                                        | Date       |
|-----------|------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|------------|
| 0.1       | First copy of the preliminary datasheet                                                                                                                                            | 13.10.2020 |
| 0.2       | Second copy of the preliminary datasheet                                                                                                                                           | 25.06.2021 |
| 1.0       | First release of the datasheet                                                                                                                                                     | 17.01.2022 |
| 1.1       | Updated Storage condition, assembly instruction and minor cosmetic changes                                                                                                         | 13.06.2022 |
| 1.2       | Storage during transportation, resolved ambiguity before paragraph 4.1.5, updated the baking time in assembly instruction and minor cosmetic changes                               | 21.09.2022 |
| 1.3       | Correction made in Storage condition section (non-evacuated instead of evacuated dry-pack). Note on typical sampling rate and sensor performance added. Parameter resolution added | 21.11.2022 |
| 1.4       | Halogen-free and RoHS symbol and storage time added/updated                                                                                                                        | 06.03.2024 |
| 1.5       | New OPN and SP#                                                                                                                                                                    | 09.04.2024 |
| 1.6       | Typ. Accuracy spec for high CO <sub>2</sub> concentration introduced, features list updated, footnote on uncertainty of calibration gas mixtures added.                            | 26.08.2024 |

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